

	AVL Supermicro server platform Memory Module Qualification Test		
	Intel X5650(WSM) x 2, Intel 5520 (Tylersburg), Rev C2	Test Results	Pass
	PN: KVR1333D3LD4R9S/16GHM (16GB / RDIMM / ECC) On: X8DTT-F Rev.1.02		

RP77D3x-106-KI-SQ-SMC-V1		Module Information		Rev 01/07/2011
AVL WorkOrder #	WC3426	AVL A#	7870	
Start Date	5/22/2012	End Date	5/29/2012	
Tested By	Andy C.			
Module Manufacturer	Kingston			
Module Part Number	KVR1333D3LD4R9S/16GHM			
Module BOM Number	9965516-C08.A00LF			
Module Capacity / Memory Type / ECC	16GB / RDIMM / ECC			
Module Configuration (Width, # of devices, # of Ranks)	2Gx72 /36 Devices / 2 Ranks			
Speed Tested (Data rate of Mbps, CL-tRP-tRCD)	DDR3L-1333 /9-9-9			
DRAM Device Vendor	Hynix			
DRAM Device Part Number / Date code	H5TC4G43MFR-H9A	1209		
DRAM Die Revision / Process Technology (nm)				
DRAM Device Config (Density / Width)	4Gbit / x4 / 1024Mx4bit			
Thermal Sensor Device Vendor / Part Number / Revision				
Register Device Vendor / Part Number / Revision				



Platform System Information				
Motherboard Info (Model# & MB Revision & MB S/N & AVL S/N)	X8DTT-F	1.02	OM03S39747	SK4376
BISO Revision / BIOS Date / MRC Rev.	2.0c	8/30/2011	2.21	
CPU / Speed	Intel X5650(WSM) x 2		2.66GHz	
Chipset info (Stepping)	Intel 5520 (Tylersburg), Rev C2			



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Test Results:

PASS

Comments:

AVL Memory Module Qual Test Results Summary

Test # and name	Test Description	Specs	Test Results	Comments
1. Latest BIOS Upgrade & Configuration	Download / Upgrade latest BIOS & record size and speed detection	Per test platform, DIMM & config spec	Done	Record memory size & speed at each test only
2. SPD Check	Memory module SPD content check for JEDEC compliance	JEDEC	Pass	Use proprietary tools
3. Sisoftware Sandra Benchmark	Run Windows based diags & utility software @50°C - DIMM max loading. Test run under 1.35v	1 loop per config	Done	Force 1066 in BIOS
4. Passmark Burn-In		6 Hour per config	Pass	Force 1066 in BIOS
5a. Stress Application Test	Run Linux based diags & utility software @50°C - DIMM max loading. Test run under 1.35v	8 Hour per config	Pass	Force 1066 in BIOS
5b. Stream Benchmark Test		5 loop per config	Done	Force 1066 in BIOS
5c. Reset Cycle		500 loop per config	Pass	Force 1066 in BIOS
6. Functional Stress Test (Corner 1)	Run RST Premium @50°C - 1 DIMM Per Ch Test run under 1.35v 1333	8 Hour or 2+ Loops per config	N/A	Run @ Max module speed
7. Functional Stress Test (Corner 2)	Run RST Premium @50°C - 2 DIMM Per Ch Test run under 1.5v	8 Hour or 2+ Loops per config	Pass	Full Load
8. Functional Stress Test (Corner 3)	Run RST Premium @0°C1 DIMM Per Ch Test run under 1.35v 1333	8 Hour or 2+ Loops per config	N/A	Run @ Max module speed

Note: All test under IMC Vdd=Nom, Vref=Vddnom/2



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AVL's DDR3 Memory Module SPD Check

Test Results:	Pass
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General Information			
AVL W/O#	WC3426	AVL A#	7870
JEDEC Speed Grade	DDR3L-1333	DRAM Density	16GB
JEDEC Raw Card#	E	Module Type	/ RDIMM
Module ECC or Non-ECC	/ ECC	Test By	

General Information			
Supplier		Module P/N	
Kingston Technology		9965516-031.A00LF	
Module Type	RDIMM	CAS Latency Supported	
Memory Type	DDR3	6,7,8,9	
SPD Rev.	1.0	Total SPD Bytes	256
CRC Coverage	0~116	SPD Bytes Used	176
tCK	1.5 nS	tRAS	36 nS
tRP	13.125 nS	tWR	15 nS
tAA	13.125 nS	tFAW	30 nS
tRC	49.125 nS	tWTR	7.5 nS
tRTP	7.5 nS	tRCD	13.125 nS
tRFC	260 nS	tRRD	6 nS

SDRAM Attributes	
SDRAM Density	4 Gb
# of Banks	8
Column Address Bits	11
Row Address Bits	16
SDRAM Device Type	Standard monolithic
SDRAM Device Width	4 bits

SDRAM Optional Feature Support			
Extended Temp Refresh Rate		2X	
Extended Temp Range		0~95	
RZQ/7	Yes	RZQ/6	Yes
ASR	Yes	DLL-Off Node	Yes
PASR	No	ODTS Readout	No

Module Attributes	
Module Thermal Sensors	Yes
Primary Bus Width	64 bits
Bus Width Extension	8 bits (ECC)
# of Ranks	2
For either UDIMM or RDIMM R/C# JEDEC Spec	
Nominal High Max in mm	29 < height <= 30 mm
Max Thickness (Front)	1 < thickness <= 2 mm
Max Thickness (Back)	1 < thickness <= 2 mm
Reference Raw Card	E
Reference Raw Card Rev.	2
Rank 1 Mapping (UDIMM)	

RDIMM Only					
Register Supplier	Inphi Corporation	# of Rows of DRAMs	2	Heat Spreader Used	Not incorporated
Register Type	SSTE32882	# of Registers Used	1	Register Revision	2.1